L Number	Hits	Search Text	DB	Time stamp
1	21	alignment adj tolerance adj range	USPAT;	2004/07/20 14:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
3	150	(alignment adj tolerance) and (common adj	USPAT;	2004/07/20 14:39
		substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
4	10	   (alignment adj tolerance) and (common adj	IBM_TDB USPAT;	2004/07/20 14:31
"	10	carrier)	US-PGPUB;	2004/07/20 14.31
		Carron	EPO; JPO;	
			DERWENT;	
			IBM TDB	
5.	7	first adj alignment adj tolerance	USPAT;	2004/07/20 14:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
6	9	second adj alignment adj tolerance	USPAT;	2004/07/20 14:36
			US-PGPUB;	
.			EPO; JPO;	
			DERWENT;	
,	C40	(alignment add telements) and (market)	IBM TDB	2004/07/20 14:41
7	642	(alignment adj tolerance) and (package)	USPAT; US-PGPUB;	2004/07/20 14:41
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	46	(alignment adj tolerance) and (integrated	USPAT;	2004/07/20 14:43
*		adj chips)	US-PGPUB;	2001, 01, 20 21110
			EPO; JPO;	·
			DERWENT;	
			IBM TDB	
9	178	(alignment adj tolerance) and (integrated	USPAT;	2004/07/20 14:49
		adj circuit adj chips)	US-PGPUB;	
	:		EPO; JPO;	
			DERWENT;	
10	10	(alignment adi telemenge) and (plumplitu	IBM_TDB   USPAT;	2004/07/20 15:08
10	10	(alignment adj tolerance) and (plurality adj packages)	US-PGPUB;	2004/07/20 15:08
		adj packages;	EPO; JPO;	1
			DERWENT;	
			IBM TDB	i i
11	18	(alignment adj tolerance) and (plurality	USPAT;	2004/07/20 15:08
		near packages)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	4254445.pn.	USPAT;	2004/07/15 17:35
· · ·			-US-PGPUB;-	
			EPO; JPO;	
			DERWENT;	
_	2	6163068.pn.	IBM_TDB USPAT;	2004/07/15 17:47
-	2	0103000.pit.	US-PGPUB;	2004/07/13 17:47
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
-	2	6362117.pn.	USPAT;	2004/07/15 17:52
		<u>-</u>	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	4326180.pn.	USPĀT;	2004/07/15 17:52
			US-PGPUB;	
			EPO; JPO;	· ·
			DERWENT;	
	L		IBM_TDB	

	14	(common adj carrier) and (integrated adj chips) and (substrate)	USPAT; US-PGPUB; EPO; JPO;	2004/07/15 17:57
_	7	(common adj carrier) with (integrated adj circuit adj chips)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/15 17:59
-	41	(common adj carrier) with (integrated adj circuits)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/15 18:03
-	19	(common adj carrier) with (ic)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/15 18:13
-	8	(common adj carrier) and 257/685.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/15 18:30
-	471	257/685.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/20 09:32
-	6	integrated adj chip adj array	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/15 18:35
_	894	integrated adj circuit adj array	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/19 11:45
-	783	package adj array	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/19 11:56
_	291	(integrated adj circuit adj array) and 257/\$.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/19 11:46
-	307	(package adj array) and 257/\$.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2004/07/19 12:27
_	707	(chip adj array) and 257/\$.ccls.	-EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/19 12:33
_	117	(semiconductor adj chip adj array) and 257/\$.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/07/20 09:18
_	1907	257/723.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20 10:15
			IBM TDB	·

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-	6	747966.pn.	USI	PAT;	2004/07/20	14:14
			US-	-PGPUB;		
			EPC	0; JPO;		
			DEF	RWENT;		
			· IBM	M TDB		